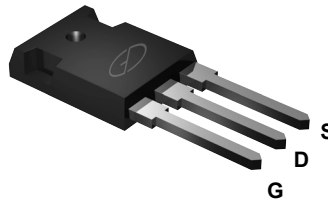
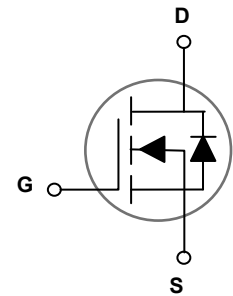


Main Product Characteristics

V_{DS}	1500V
$R_{DS(ON)}$	10 Ω
I_D	2.5A



TO-247



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFA15002 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	1500	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current ($T_C=25^{\circ}\text{C}$)	$I_D (DC)$	2.5	A
Continuous Drain Current ($T_C=100^{\circ}\text{C}$)	$I_D (DC)$	1.6	A
Pulsed Drain Current ¹	$I_{DM (pluse)}$	10	A
Maximum Power Dissipation ($T_C=25^{\circ}\text{C}$)	P_D	100	W
Power Dissipation-Derate Above 25 $^{\circ}\text{C}$		0.8	W/ $^{\circ}\text{C}$
Single Pulse Avalanche Energy ²	E_{AS}	36.5	mJ
Avalanche Current ²	I_{AS}	2.7	A
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.25	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^{\circ}\text{C}/\text{W}$
Operating Junction Temperature Range	T_J	-55 to +150	$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150	$^{\circ}\text{C}$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
On/off States						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	1500	-	-	V
Zero Gate Voltage Drain Current($T_C=25^\circ\text{C}$)	I_{DSS}	$V_{DS}=1200V, V_{GS}=0V$	-	-	1	μA
Zero Gate Voltage Drain Current($T_C=85^\circ\text{C}$)	I_{DSS}	$V_{DS}=960V, V_{GS}=0V$	-	-	10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 30V, V_{DS}=0V$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3.2	5	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=2A$	-	7	10	Ω
Forward Transconductance	g_{fs}	$V_{DS}=10V, I_D=1A$	-	1	-	S
Gate Resistance	R_g	$V_{GS}=0V, V_{DS}=0V, F=1.0\text{MHz}$	-	5.6	-	Ω
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=100V, V_{GS}=0V,$ $F=1.0\text{MHz}$	-	1150	2300	pF
Output Capacitance	C_{oss}		-	50	100	pF
Reverse Transfer Capacitance	C_{rss}		-	23	46	pF
Total Gate Charge ^{3,4}	Q_g	$V_{DS}=100V, I_D=1A,$ $V_{GS}=10V$	-	41	82	nC
Gate-Source Charge ^{3,4}	Q_{gs}		-	12	24	nC
Gate-Drain Charge ^{3,4}	Q_{gd}		-	12.4	25	nC
Switching Times						
Turn-on Delay Time ^{3,4}	$t_{d(on)}$	$V_{DD}=100V, I_D=1A,$ $R_G=6\Omega, V_{GS}=10V$	-	38	70	nS
Turn-on Rise Time ^{3,4}	t_r		-	32	65	nS
Turn-Off Delay Time ^{3,4}	$t_{d(off)}$		-	48	95	nS
Turn-Off Fall Time ^{3,4}	t_f		-	45	90	nS
Source- Drain Diode Characteristics						
Source-Drain Current(Body Diode)	I_S	$V_D=V_G=0V, \text{Force Current}$	-	-	2.5	A
Pulsed Source-Drain Current(Body Diode)	I_{SM}		-	-	5.0	A
Forward On Voltage	V_{SD}	$T_J=25^\circ\text{C}, I_S=1A, V_{GS}=0V$	-	-	1.0	V
Reverse Recovery Time	t_{rr}	$T_J=25^\circ\text{C}, I_S=I_F=2A,$ $di/dt=100A/\mu S$	-	1.83	-	μS
Reverse Recovery Charge	Q_{rr}		-	48.7	-	μC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. $V_{DD}=100V, V_{GS}=10V, L=10\text{mH}, I_{AS}=2.7A, R_G=25, \text{Starting } T_J=25^\circ\text{C}.$
3. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

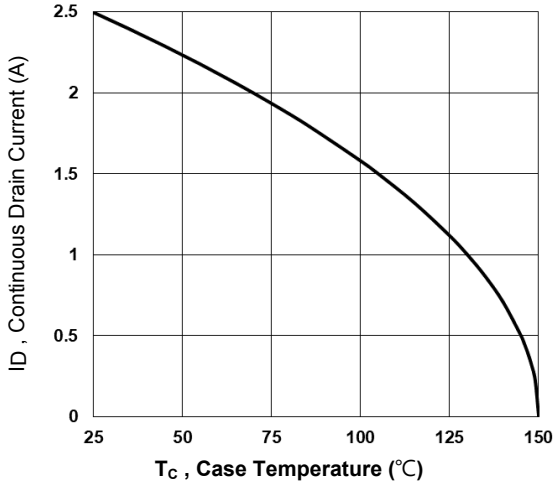


Fig.1 Continuous Drain Current vs. T_c

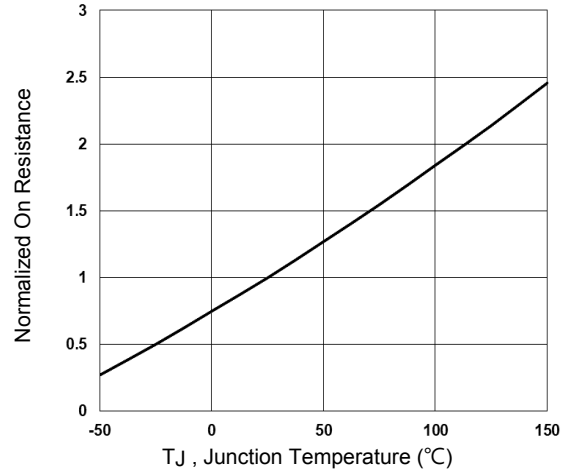


Fig.2 Normalized RD_{SON} vs. T_J

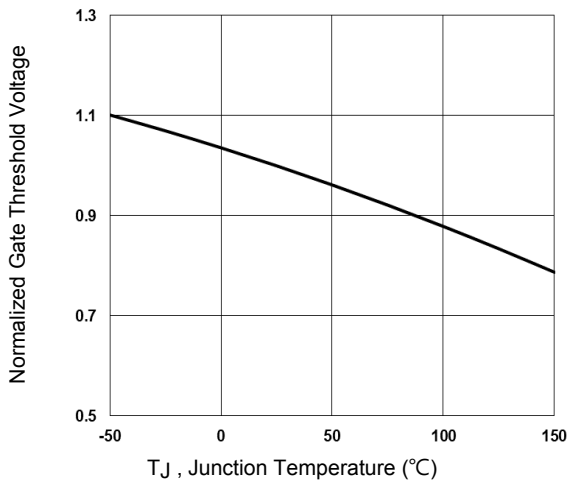


Fig.3 Normalized V_{th} vs. T_J

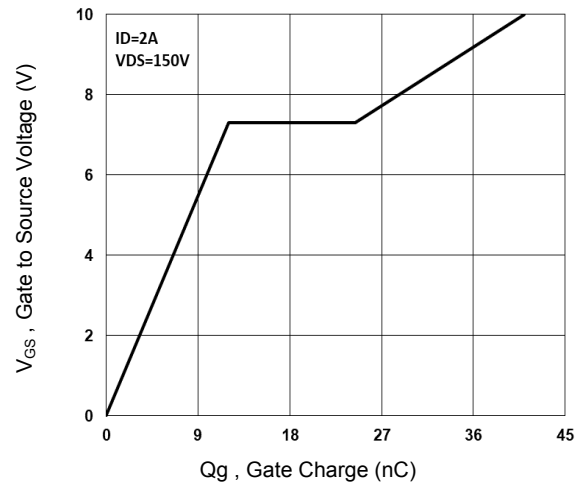


Fig.4 Gate Charge Characteristics

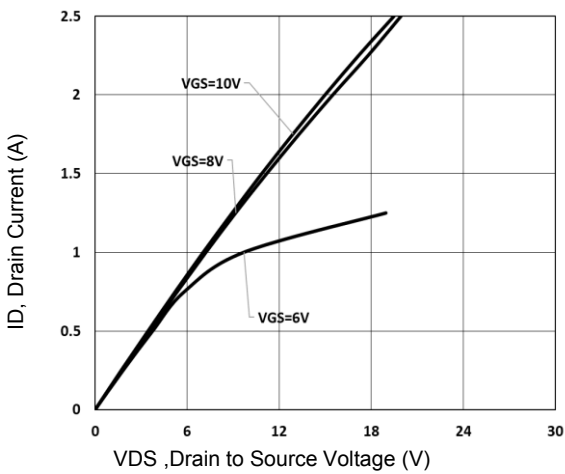


Fig.5 Typical Output Characteristics

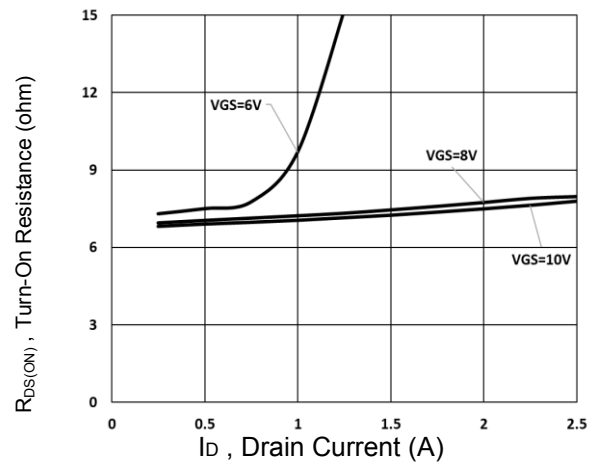


Fig.6 Turn-On Resistance vs. I_D

Typical Electrical and Thermal Characteristic Curves

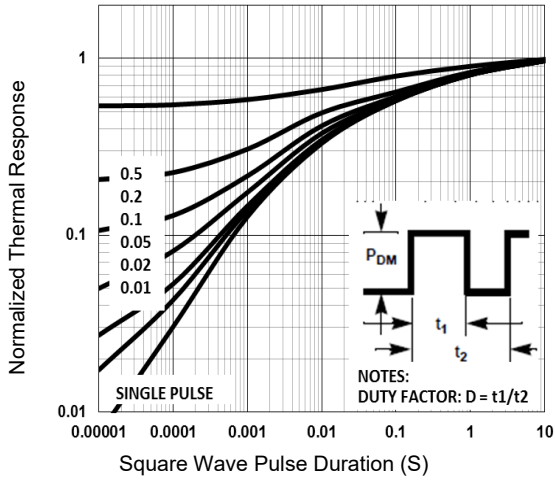


Fig.7 Normalized Transient Impedance

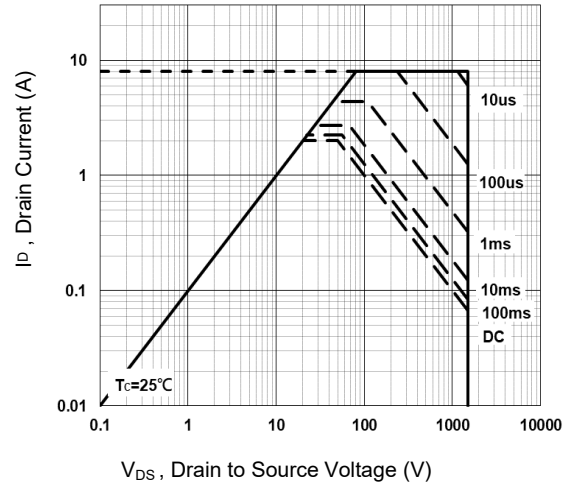


Fig.8 Maximum Safe Operation Area

Test Circuits & Waveforms

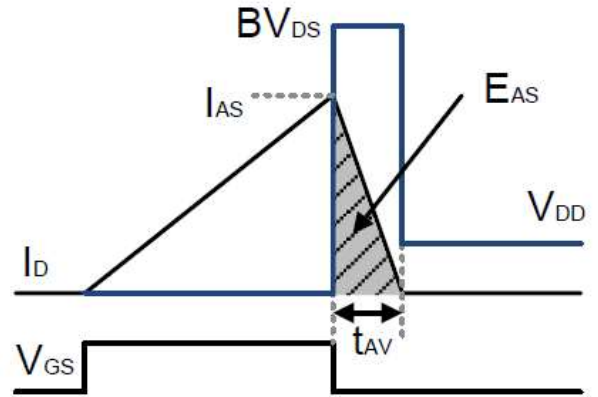
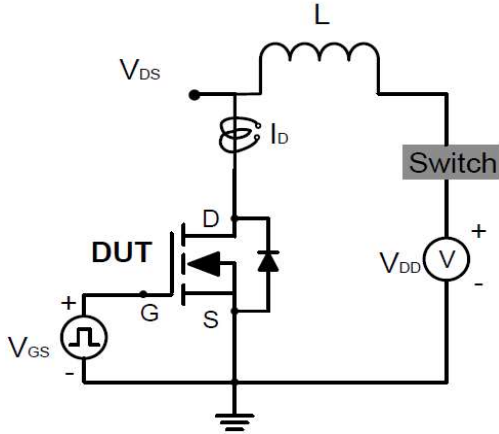


Figure 9. E_{AS} Test Circuit and waveforms

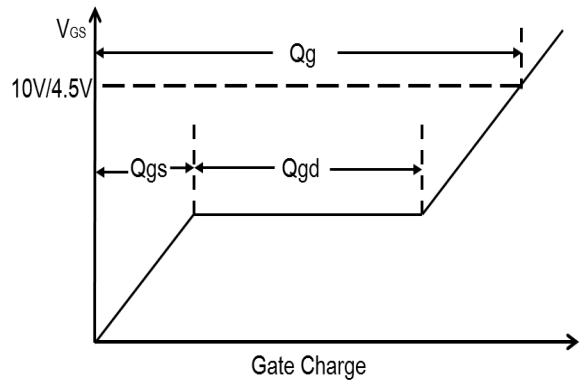
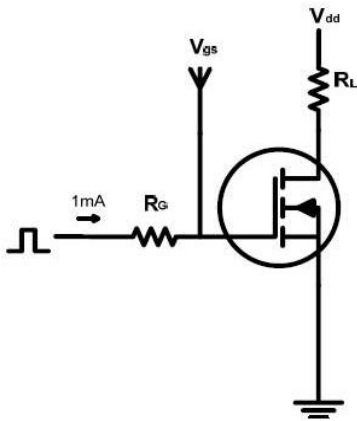


Figure 10. Gate Charge Test Circuit and waveforms

Switch Time Test Circuit:

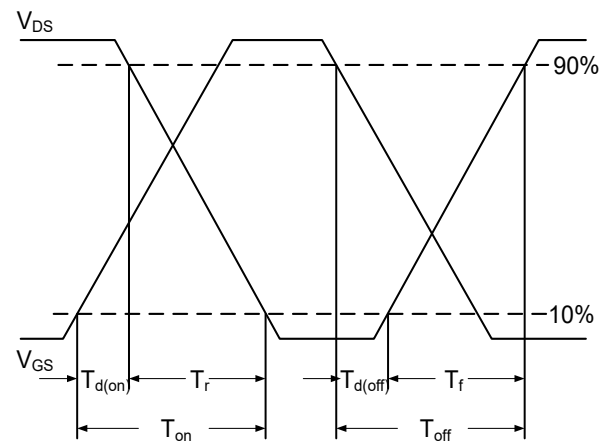
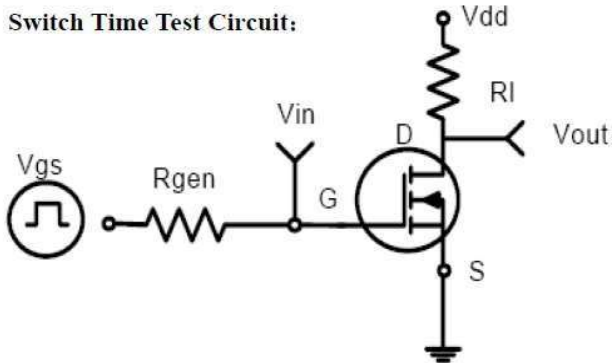
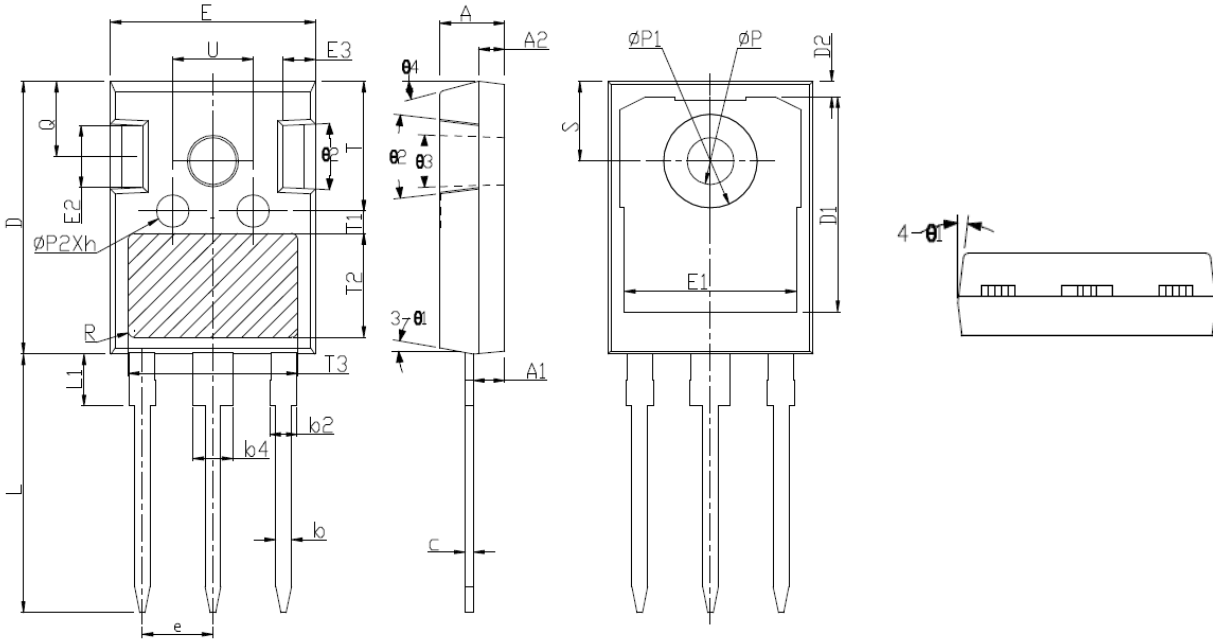


Figure 11. Switch Time Test Circuit and waveforms

Package Outline Dimensions TO-247



SYMBOL	mm			SYMBOL	mm		
	MIN	NOM	MAX		MIN	NOM	MAX
A	4.75	5.00	5.25	L	19.52	19.92	20.32
A1	2.16	2.41	2.66	L1	-	-	4.30
A2	1.85	2.00	2.15	ΦP	3.35	3.60	3.85
b	1.11	1.20	1.35	ΦP1	-	-	7.30
b2	1.90	2.01	2.25	ΦP2	2.25	2.50	2.75
b4	2.90	3.10	3.25	Q	5.50	5.80	6.10
c	0.51	0.61	0.75	S	6.15BSC		
D	20.60	21.00	21.40	R	0.50REF		
D1	16.15	16.55	16.95	T	9.70	-	10.30
D2	1.00	1.20	1.40	T1	1.65REF		
E	15.50	15.80	16.10	T2	8.00REF		
E1	13.00	13.30	13.60	T3	12.80REF		
E2	4.70	5.00	5.30	U	5.9	-	6.5
E3	2.25	2.50	2.75	θ1	4°	7°	10°
e	5.44BSC			θ2	2°	5°	8°
h	0.00	0.10	0.25	θ3	1°	-	2°
				θ4	10°	15°	20°